

# SMP BOND

1-COMPONENT SMP ADHESIVE FOR WOOD FLOORING ACCORDING TO DIN 14 293



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## DESCRIPTION:

One-component moisture cured SMP adhesive according to DIN 14 293, solvent and water free, for solid, on-edge wood flooring 16 – 22 mm, multi-ply/pre-finished wood flooring, solid boards, exotic timbers. Suitable for the application on absorbent and non absorbent subfloors. Indoor use.

Suitable for castor chairs (DIN EN 12 529)

Suitable on warm water underfloor heating

- Solvent and water free
- Tin- and heavy metals free
- Combines high strength with a useful elasticity
- Hard elastic adhesive ridges
- Neutral odour
- Dissipates shear forces
- Adhesive residues easy to remove
- Easy to spread

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## TECHNICAL DATA:

Chemical base:	modified silane prepolymer
Cure mechanism:	hygro-hardening
Colour:	beige
Specific weight:	1,65 g/cm
<b>Solid content:</b>	<b>100% - free of solvent and PVC</b>
<b>Hardness Shore A:</b>	<b>40 - 50 (DIN 53 505)</b>
<b>Elongation at break:</b>	<b>100% - 120% (DIN 53 504)</b>
<b>Lap shear strength:</b>	<b>1,9 mPa.s (DIN 14 293)</b>
<b>Tensile strength:</b>	<b>1,9-2 mPa.s (DIN 53 504)</b>
Pot life:	approx. 40 minutes
Working time:	approx. 40 minutes
Application:	with notched trowel TKB B5 – TKB B11
Average Consumption:	800 - 1200 gr/m <sup>2</sup> depending on trowel and substrate
Working temperature:	not less than +10°C/50°F
Load bearing:	after approx. 24 - 48 hours
Sanding/Sealing:	after approx. 24 - 48 hours
Final strength:	after 3-5 days
Shelf life:	12 months in unopened packaging.
Storage temperature:	between +5°C/41°F and +25°C/77°F
Emicode:	EC1R – water/solvent free in accordance with TRGS 610
Packaging:	plastic drum
Pack size:	15 kg

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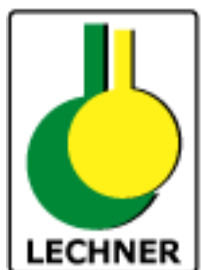
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**SUBSTRATE PREPARATION:** The substrate must be sound, level, dry, free from cracks, clean and free from materials that would impair adhesion in according to DIN 18365, 18356, 18352 and ÖNorm B2218, B2236. Prior to starting an application, individual substrates should be evaluated. Inspect the concrete and remove loose or soft concrete, separating agents, loose residues of adhesive, smoothing compounds, coverings or coatings by brushing, abrading, grinding. Cement- and calcium sulphate-screeds must be sanded (grain 16) and vacuumed. Thoroughly vacuum off any loose material and dust. On very uneven surfaces prime with Primer PU 300 / Primer PU 150 Speed or Primer PU and apply fibre reinforced self levelling compound Fibrodur or very rapid cement smoothing compound Levelfast. On ceramic tiles use Promox.

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**INSTRUCTION FOR USE:** Before use, allow canister to come to room temperature. Apply the adhesive evenly onto surface using a suitable notched trowel. Only apply as much adhesive as can be covered within 40 minutes. The use of wood flooring not dried according to standards can, in the event of increase in air humidity, lead to damage from swelling. Leave a gap of 10 – 15 mm between wall and wood flooring. To remove fresh, dried or cured adhesive residues from wear surfaces such as parquet use Cleancoll using a clean cloth (please test the effect of the cleaner on the surface of the wood flooring in an inconspicuous area prior to applying the cleaner). Clean tools immediately after use with Solvente CH 500 (Refer to the Technical Data sheets for the products used).



## HEADQUARTERS AND PRODUCTION PLANT

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**OTHER INFORMATION:** The following standards are applicable and recommended:

DIN 18356 "Working with wood flooring"

Notice issued by the Adhesives Industry Association "Bonding of wood flooring"

TKB publication "Assessment and preparation of substrates for floor covering and wood flooring installations"

BEB publication "Assessment and preparation of substrates".

The installation conditions are 23°C/73°F and 50% relative humidity.

Do not apply **SMP Bond** at temperature below + 10°C/50°F, at temperature of the substrate below +15°C/59°F and at relative humidity above 75%. Protect from frost. Low temperatures lengthen, whilst high temperatures shorten the pot life, working- and setting- times. Opened canister has to be used as quickly as possible. For professional use only. Subfloors sensitive to humidity must be treated accordingly to instruction of the producer. For further information please send an email to [export@lechnerspa.it](mailto:export@lechnerspa.it)

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**SAFETY INSTRUCTIONS:** Before embarking on any work ensure you are supplied with the Relevant Safety Data Sheet and have read carefully the following information.

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**DISPOSAL:** Dispose in accordance with federal, state, and local regulations. Use licensed hazardous waste company. Do not allow dispersal into drains, sewers or ground. Use barrier cream, protective gloves and safety-goggles. Provide good ventilation. For further information please send an email to [export@lechnerspa.it](mailto:export@lechnerspa.it)

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**WARRANTY STATEMENT:** This leaflet is for general guidance only and may contain inappropriate information under particular conditions of use. The company cannot accept any responsibility for loss or damage that may result from the use of this information, due to the possibility of variations of processing or working conditions and of workmanship outside our control. Users are advised to confirm the suitability of this product by their own tests. This Technical Information supersedes all other application data sheets and product information published before

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